

**PRODUCT
DATASHEET**



SMFF1206 Series Surface Mount Fuses Devices

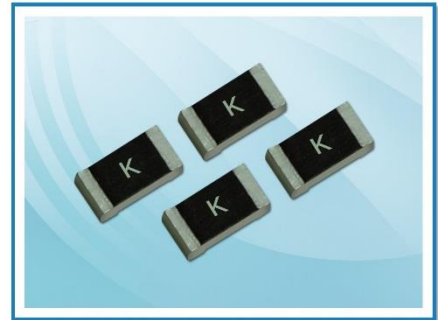
SMFF1206 Series Surface Mount Fuses Devices

Description

Polytronics SMFF1206 series surface mount fast-acting fuse utilizes thick film process with extremely stable fusing element. The glass over coating can tolerate higher temperature profile, and the non-flammable ceramic substrate offers better heat conductivity and safety. SMFF1206 series is also RoHS compliant and halogen-free to meet global environmental standard.

Features

- Fast acting
- Compact size
- Thick film manufacturing method
- Ceramic substrate with silver fusing element
- Excellent environmental integrity



Application

- Battery pack
- Digital camera
- Game equipment
- Wireless base station
- LCD monitors and modules
- PC related equipment / peripherals
- Power supply
- Medical device

Agency Approval and Environmental Compliance

Agency	File Number	Regulation	Standard
	UL/CSA:E331807		2011/65/EU
			IEC 61249-2-21:2003

Electrical Characteristics

Part Number	Marking	Current Rating (A)	Voltage Rating	Interrupting Rating	Typical Cold DCR† (Ω)	Typical I²T‡ (A²S)	Agency Approval 
SMFF1206P100	H	1.0	32V DC	50A / 32V DC	0.240	0.0279	✓
SMFF1206P150	K	1.5			0.115	0.0491	✓
SMFF1206P200	N	2.0			0.064	0.1251	✓
SMFF1206P250	O	2.5			0.033	0.1255	✓
SMFF1206P300	P	3.0			0.027	0.2880	✓
SMFF1206P350	R	3.5			0.0205	0.5366	✓
SMFF1206P400	S	4.0	32V DC	35A / 32V DC	0.0155	0.8928	✓
SMFF1206P500	T	5.0			0.0125	0.9325	✓
SMFF1206P600	6	6.0			0.0110	1.5192	✓
SMFF1206P700	U	7.0			0.0072	2.2050	✓

† Measured at ≤ 10% rated current and 25°C

‡ Melting I²T at 10 times of rated current

SMFF1206 Series Surface Mount Fuses Devices

Electrical Specification

Ampere Rating	% of Current Rating	Opening Time
1A~7A	100%	4 Hours Min.
	250%	5 Seconds Max.

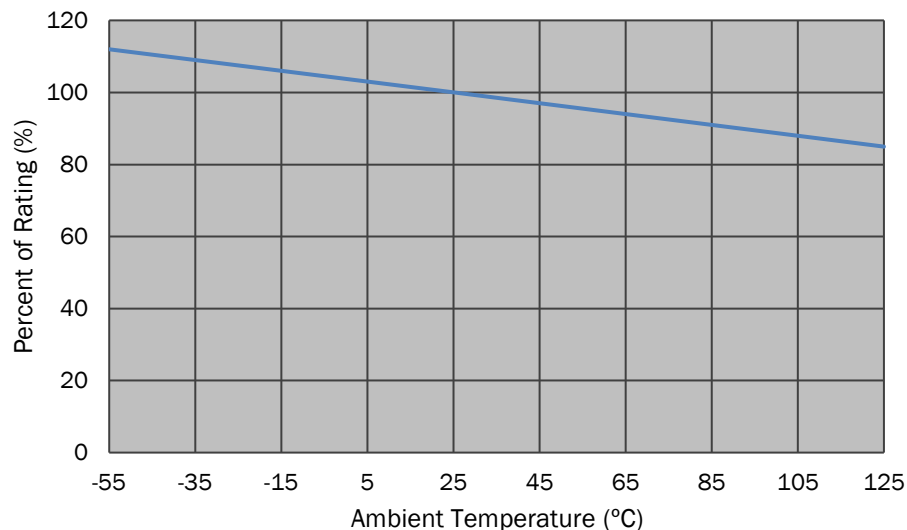
Physical Specifications

Materials	Substrate: Ceramic Terminations: Silver over-plated with 100% tin Element: Silver or Silver/palladium
Solderability	MIL-STD-202
Soldering Parameters	Wave Solder: 260 °C, 10 seconds max. Reflow Solder: 260 °C, 20 seconds max. Hand Solder: 350 °C, 5 seconds max.

Environmental Specifications

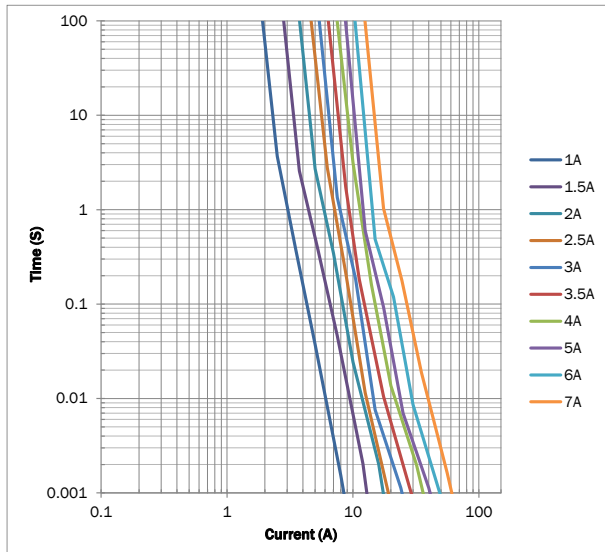
Operating Temperature	-55°C to 125°C
-----------------------	----------------

Thermal Derating Curve

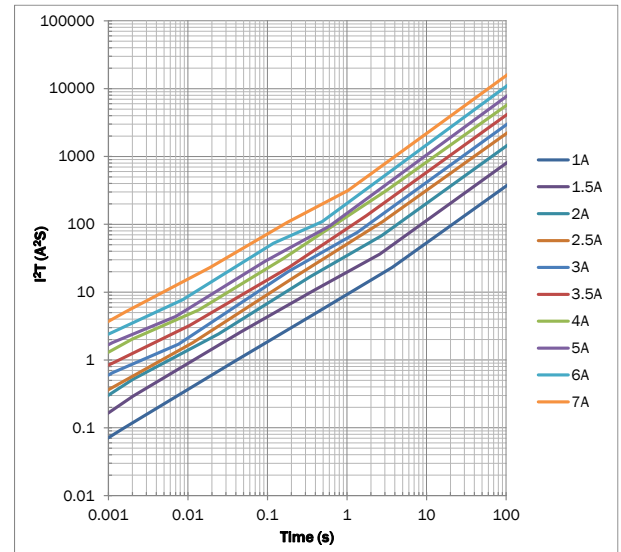


SMFF1206 Series Surface Mount Fuses Devices

Time-Current Curve



I²T vs Time Curve



Physical Dimensions (mm.)

Dimensions (mm)

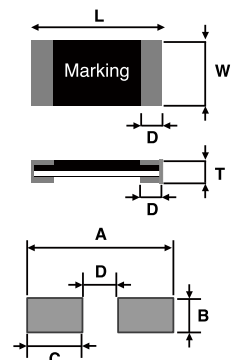
L	W	T	D
3.10±0.20	1.55±0.20	0.55±0.20	0.50±0.20

Recommended Solder Pad Dimension (mm)

A	B	C	D
4.4±0.5	2.4±0.3	1.2±0.3	2.0±0.3

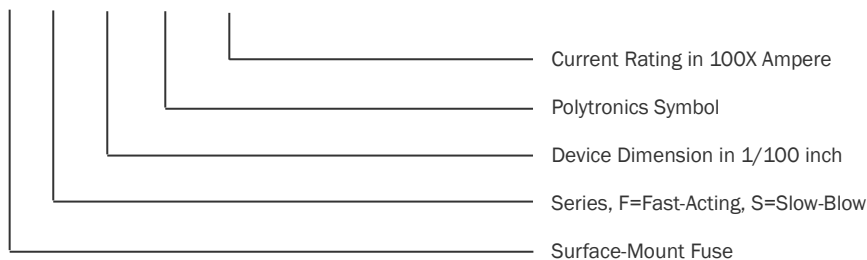
Dimensions of Standard Test Board (mm)

Ampere Rating	Board Thickness	Copper Layer Thickness	Copper Trace Width
1A~6A	1.6	0.035	5.0
7A	1.6	0.070	7.5



Part Number System

SMF F 1206 P □ □ □



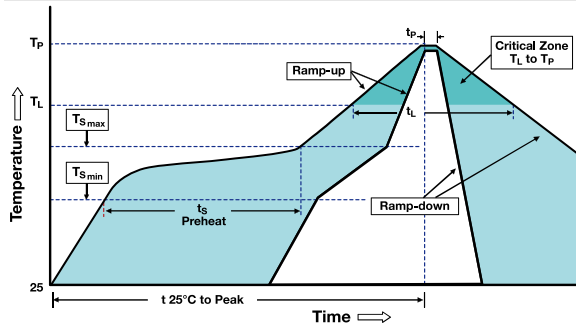
SMFF1206 Series Surface Mount Fuses Devices

Reliability Test

Characteristics	Test condition / Methods	Requirement	Test Reference
Voltage Drop	100% In	Deviation between the mean value: <15%	IEC 60127-4
Time/Current	100% In	No fusing, 4 hours min.	UL248-14
	250% In	≤ 5 sec.	Refer to Spec.
	1000%In	> 0.1 msec	IEC60127-4
Endurance Test	100% In; 1hour on, 15min off, 100cycles; then following by 1hour at 125% In	ΔR : <10%	IEC 60127-4
Temperature Rise	100% In	ΔT : <75 °C	IEC 60127-4
Interrupting Ability	50A / 32V DC (1A~3.5A) 35A / 32V DC (4A~7A)	Without permanent arcing, ignition and bursting of fuse link	UL 248-14 IEC60127-4
Solderability	240 °C ± 5 °C, 3sec ± 0.5sec	95% coverage min	IEC 60127-4 MIL-STD-202 Method 208
Resistance to Soldering	260 °C ± 5 °C, 10sec ± 0.5sec	ΔR : <10% Legible appearance	MIL-STD-202 Method 210
Bending Test	Distance between holding points: 90mm Bending: 1 mm; Time, 10 seconds	ΔR : <10% No mechanical damages	IEC 60127-4
High Temperature Operating Life	70 °C ± 2 °C at 60% In, 96 hours ;	ΔR : <10%; no fusing	MIL-STD-202 Method 108
Low Temperature Storage	-55 °C ± 3 °C, 96 hours	ΔR : <10%	IEC 60068-2-1
High temperature Storage	125 °C ± 2 °C, 96 hours	ΔR : <10%	IEC 60068-2-2
Humidity (Steady State)	40 °C ± 2 °C, 90~95%RH for 1000 hours	ΔR : <10%	MIL-STD-202 Method 103
Salt Spray	5% salt solution, 48 hours	ΔR : <10% Legible appearance	MIL-STD-202 Method 101
Thermal Shock	100 cycles between -65 °C /+125 °C 60 minutes at each extreme zone	ΔR : <10% No mechanical damage	MIL-STD-202 Method 107

SMFF1206 Series Surface Mount Fuses Devices

Soldering Parameters

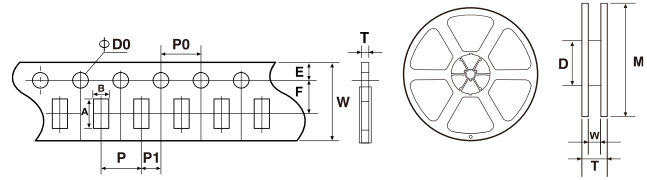


Average Ramp-Up Rate ($T_{s_{max}}$ to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{s_{min}}$)	150°C
-Temperature Max ($T_{s_{max}}$)	200°C
-Time ($T_{s_{min}}$ to $T_{s_{max}}$)	60-120 seconds
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20 seconds
Ramp-Down Rate	6°C /second max.
Time 25°C to Peak Temperature	8 minutes max.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Tape & Reel Specification (mm.)



A	3.50 ± 0.20
B	1.90 ± 0.20
W	8.00 ± 0.20
F	3.50 ± 0.05
E	1.75 ± 0.10
P	4.00 ± 0.10
P0	4.00 ± 0.10
P1	2.00 ± 0.10
D0	Ø 1.50 ± 0.10
T	0.75 ± 0.10

M	Ø178.0 ± 2.0
W	9.5 ± 1.0
T	12.5 ± 1.5
A	2.0 ± 0.5
B	Ø 13.0 ± 0.5
C	Ø 21.0 ± 0.5
D	Ø 58.0 ± 2.0

Packaging Quantity

Part Number	Tape & Reel Quantity
SMFF1206PXXX	5000

Storage

- The ambient temperature recommended for storage shall be between 5°C ~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Fuse product is not recommended for any type of coating. Polytronics is not responsible for any damage directly or indirectly related to the coating.
- For copper layer thickness or copper trace width different from the standard test board, fusing characteristics needs to be verified to ensure product performance meet user requirement.